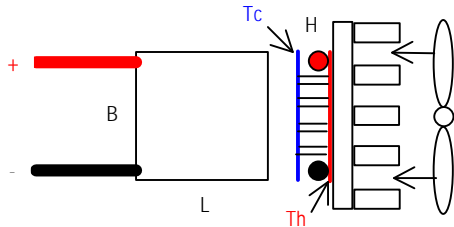


Install Diagram (wires solder side is hot side if voltage is applied like the diagram)



Specifications

Vnorm (VDC)	Vmax (VDC)	I _{max} (A)	Q _{max} (W)	Size (mm) L x B x H	Min. Fansink Size (mm)
12.0	15.4	14.0	120.0	62 x 62 x 4.6	120 x 120 x 50

A thermoelectric cooling (TEC) module is a semiconductor-based electric component that functions as a small heat pump. By applying DC power source to a TEC, heat will be transferred from one side of the module to the other. It creates a cold and hot side. They are widely used in industrial area, for example, computer CPU, CCD, Laser, portable refrigerators, medical instruments, and so on.

Installation

1. The hot surface **Th** of the TEC must be attached to a suitable FAN SINK (please refer to the table in the above) that is capable of carrying away both the heat pumped by the TEC plus Joule heat from the electric power supplied to the TEC. A heat sink rise of 15°C above ambient is typical for many TEC applications. Otherwise, a bigger heat sink must be used to reduce temperature.
2. Care should be taken when applying pressure during installation. Uniform pressure is desired across the mounting surfaces. If uneven pressure is applied, thermal performance may be reduced or damage may occur to the TEC.
3. Clean surface thoroughly, making sure there are no chips, dirt or any foreign substances that may affect bonding. Coat the contacting sides, **Th** and **Tc**, with thermally conductive grease or glue.